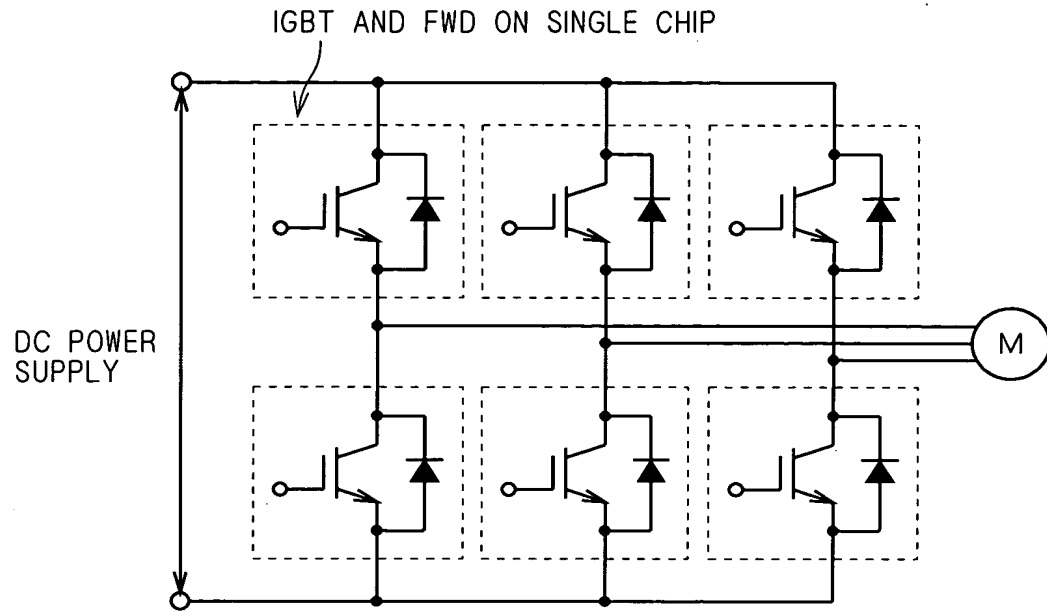


F I G . 1



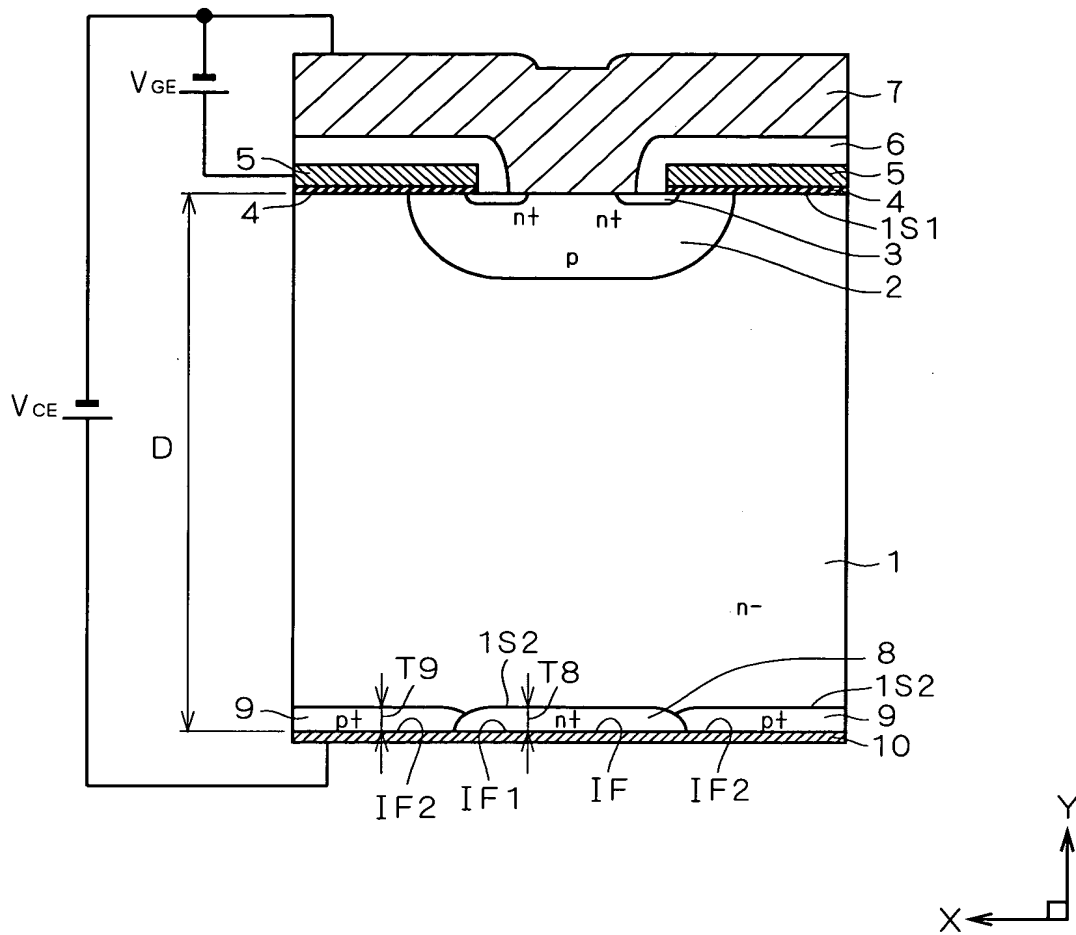


FIG. 3

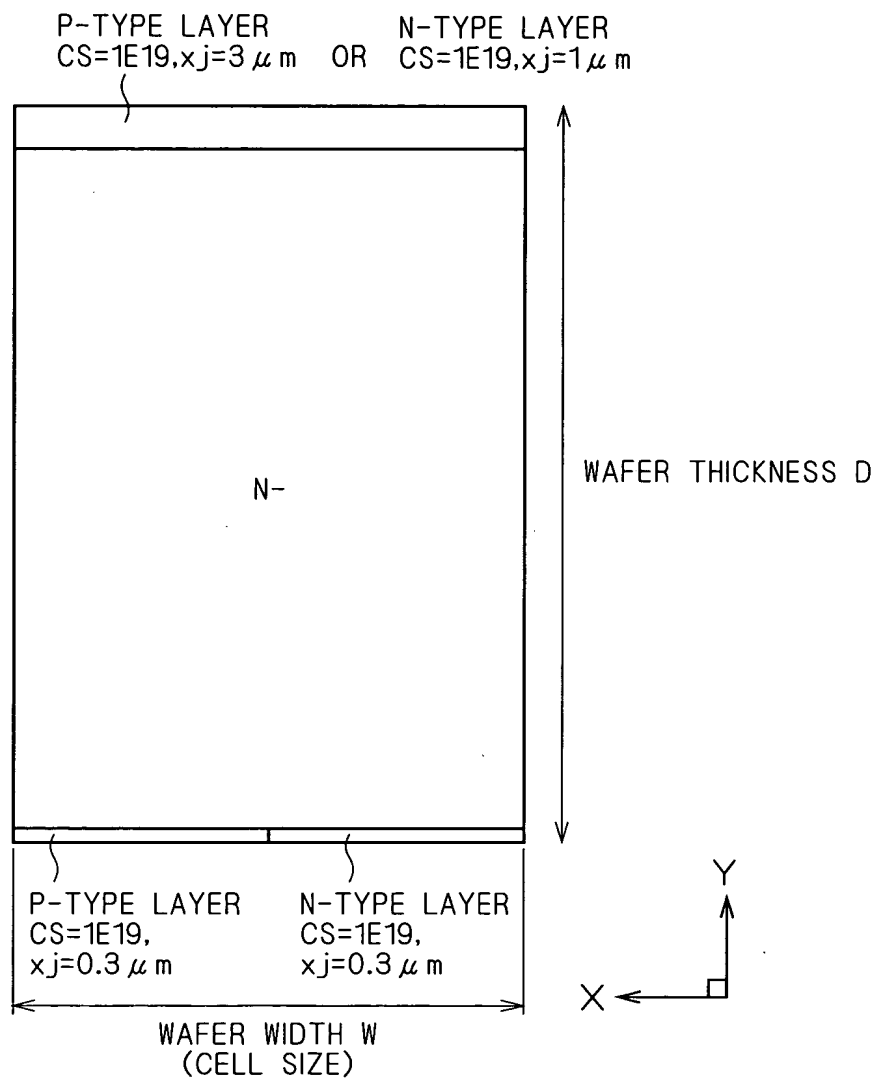


FIG. 4 A

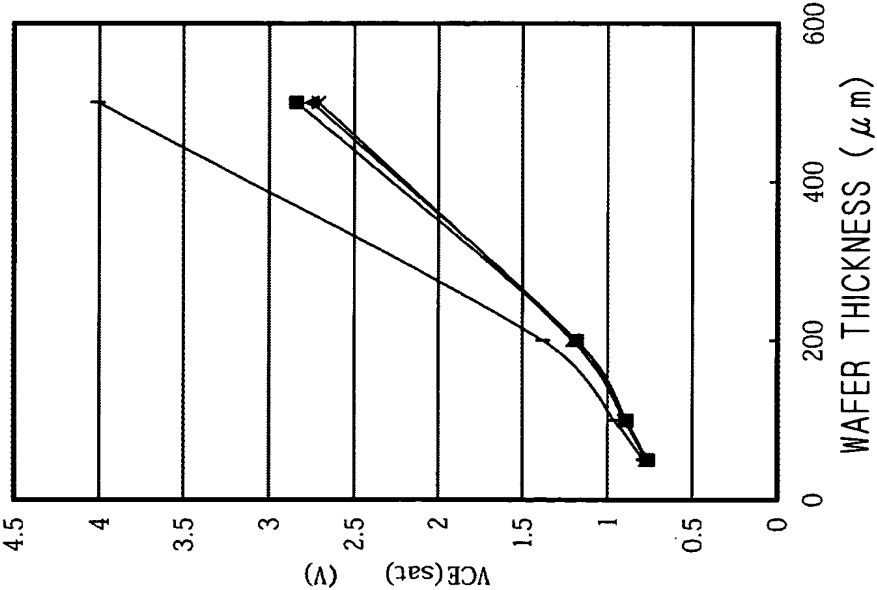
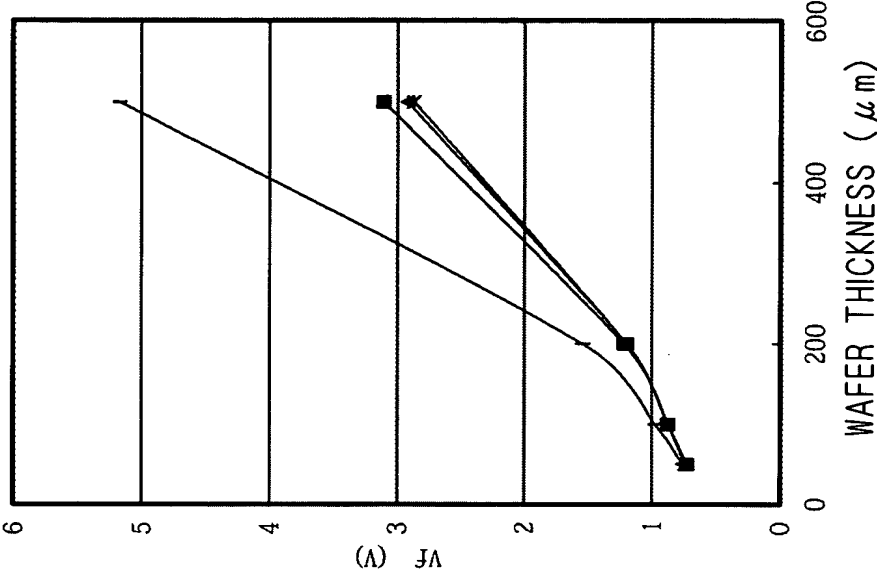
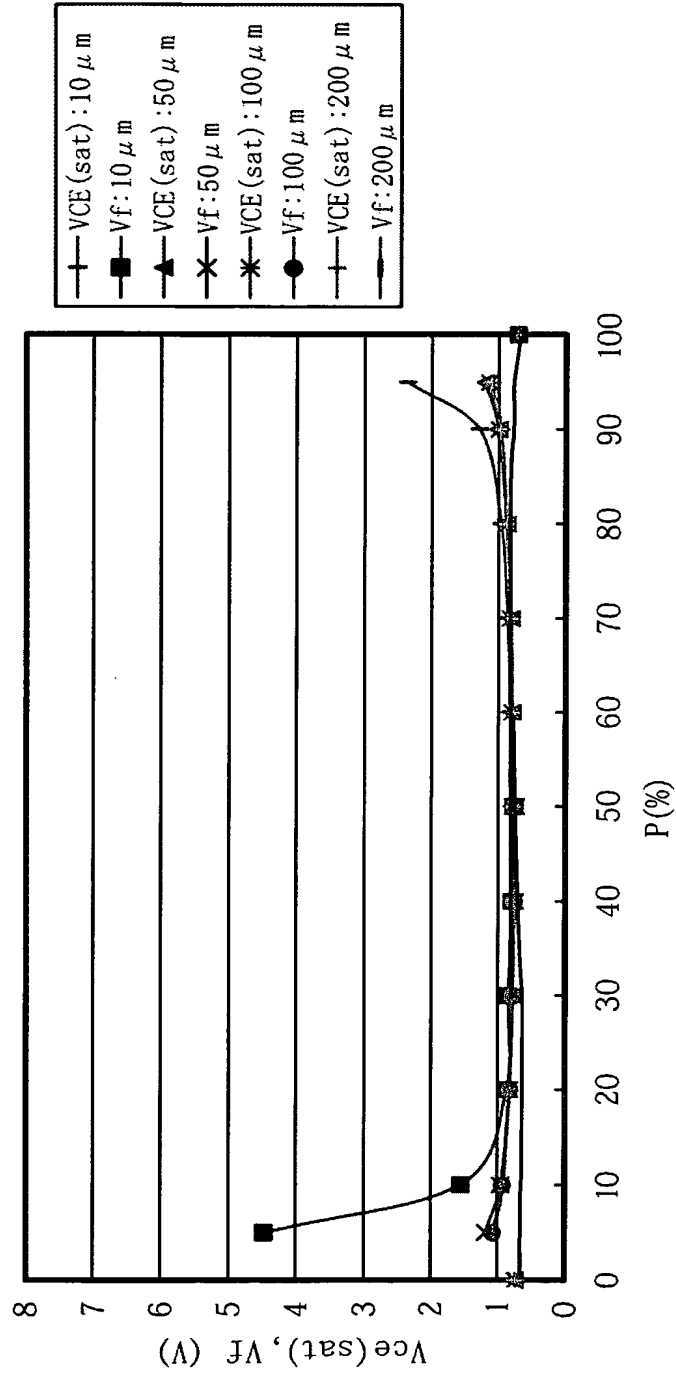


FIG. 4 B



F I G . 5

WAFER (SUBSTRATE) THICKNESS : 50 μ m



F I G . 6

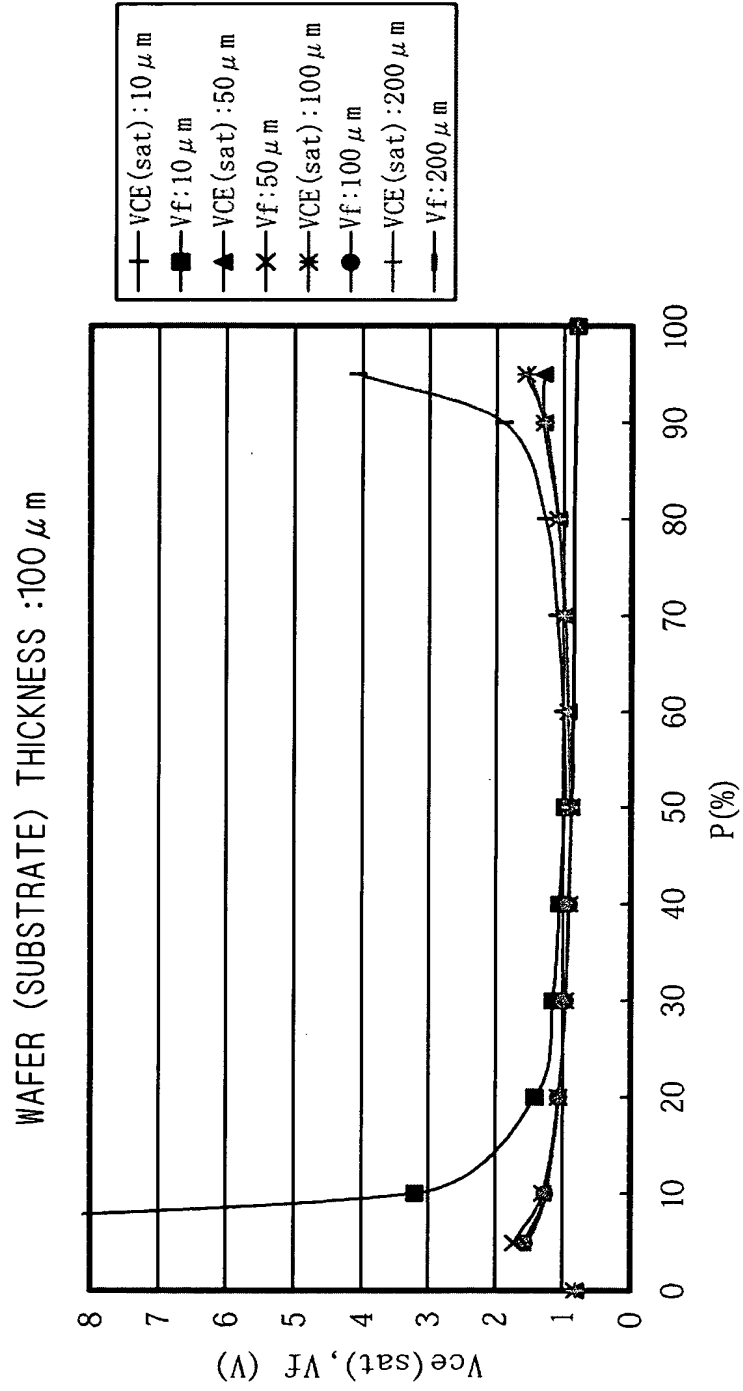
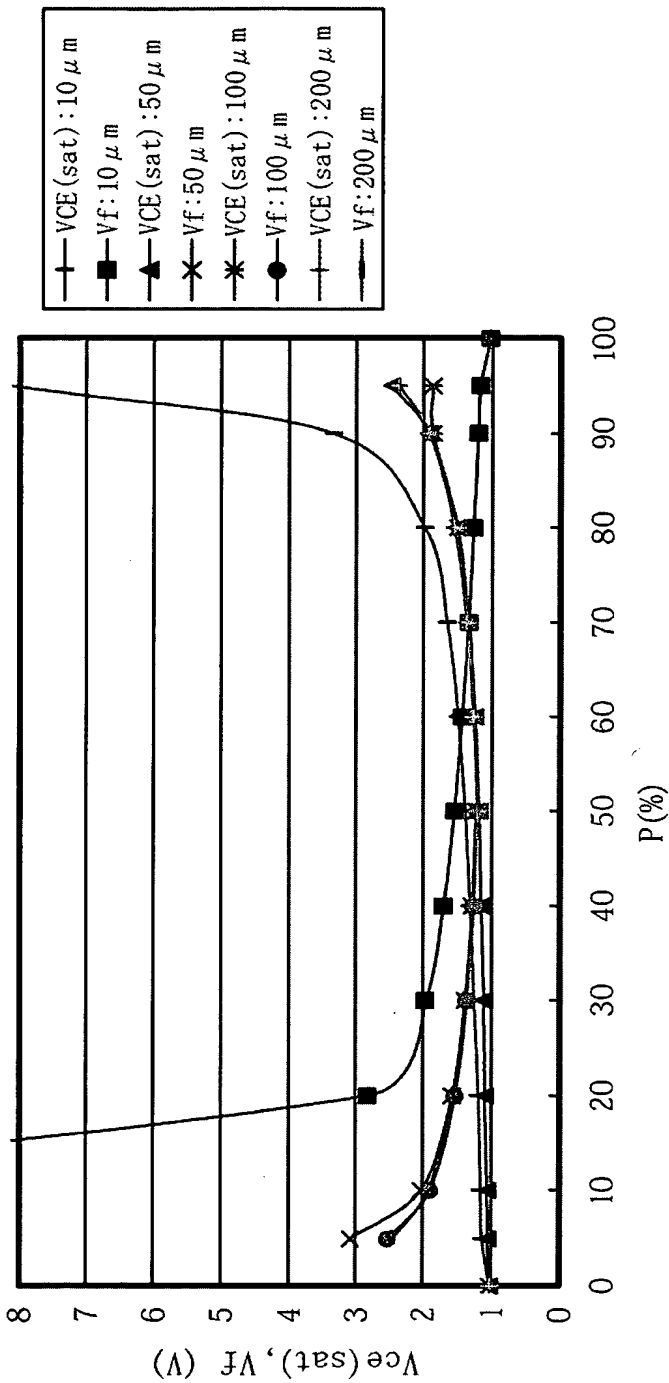
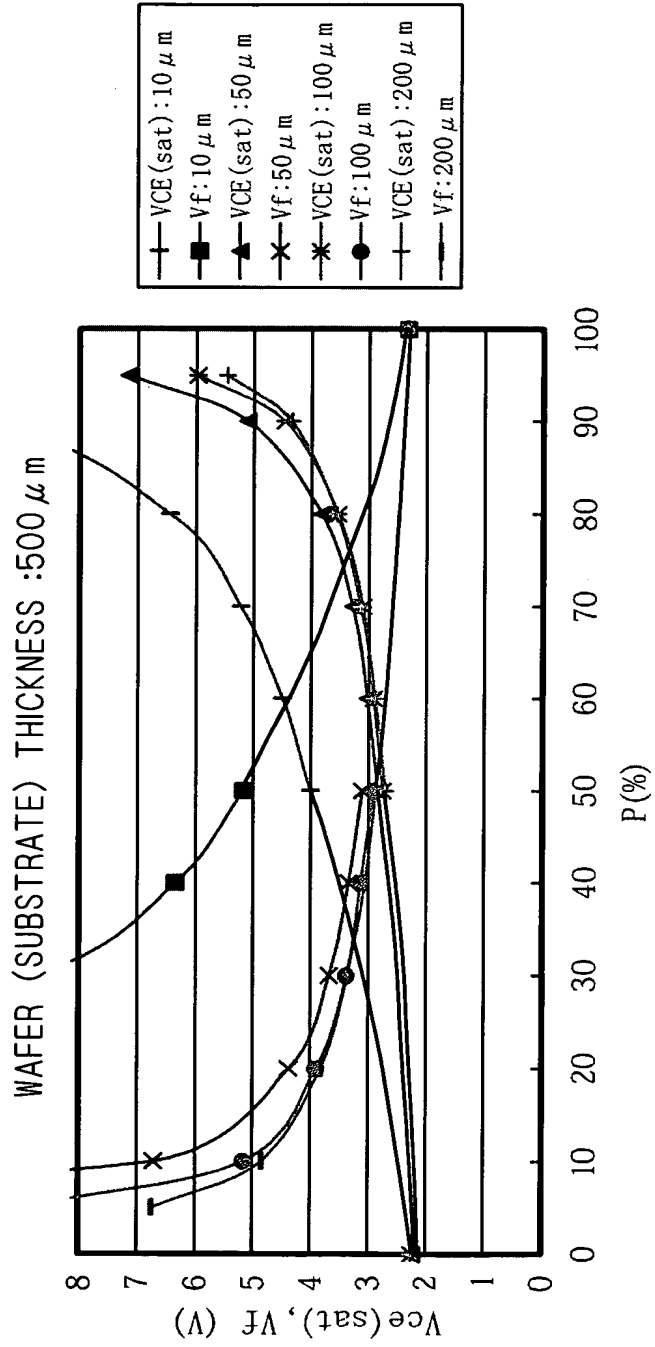


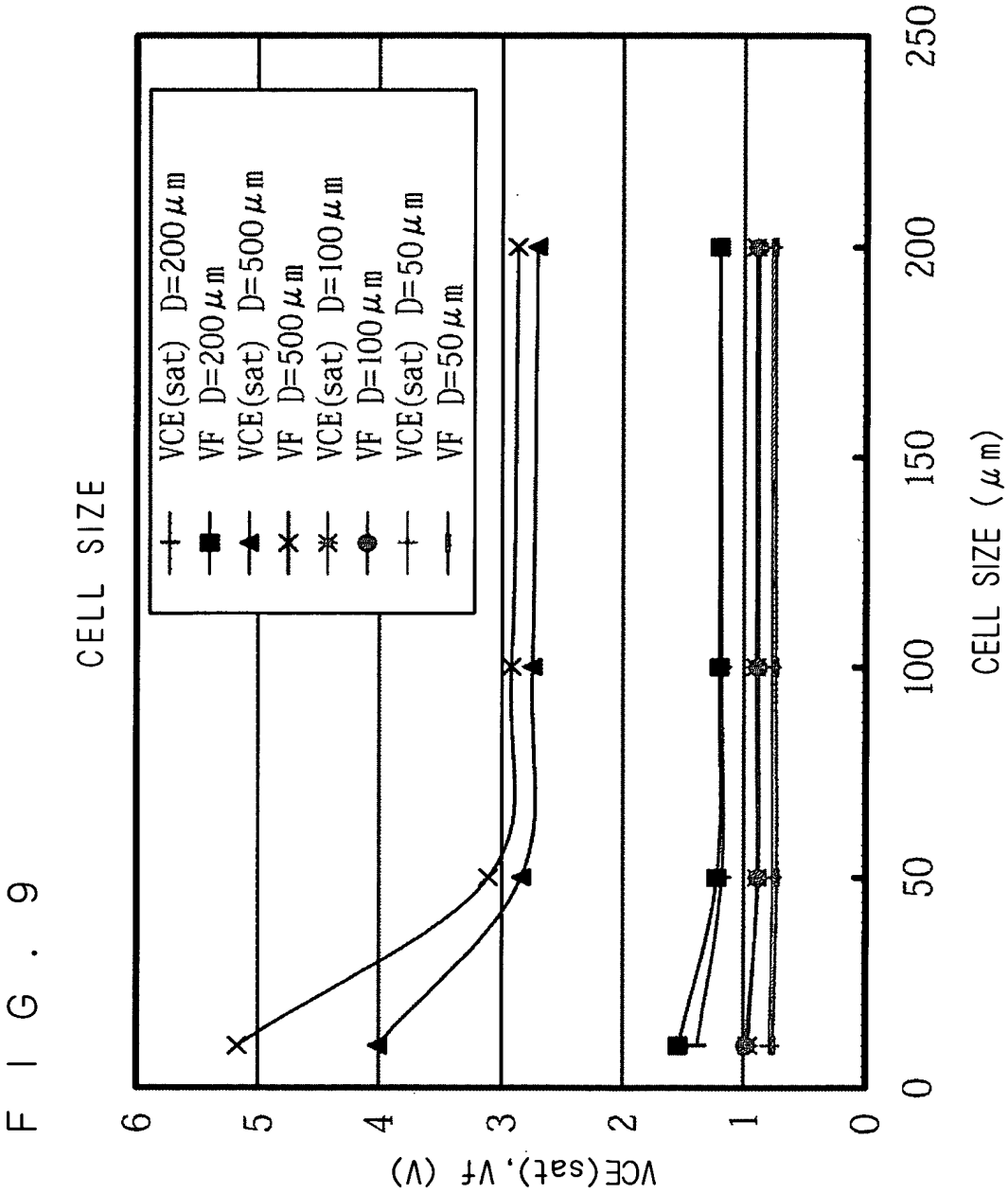
FIG. 7

WAFER (SUBSTRATE) THICKNESS : 200 μ m

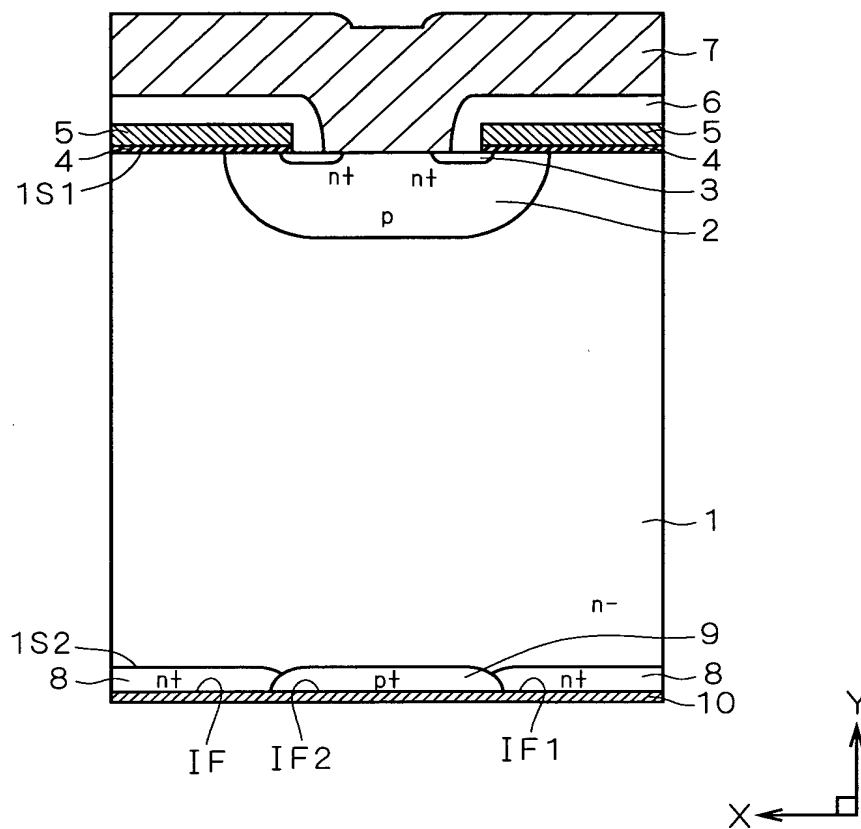


8
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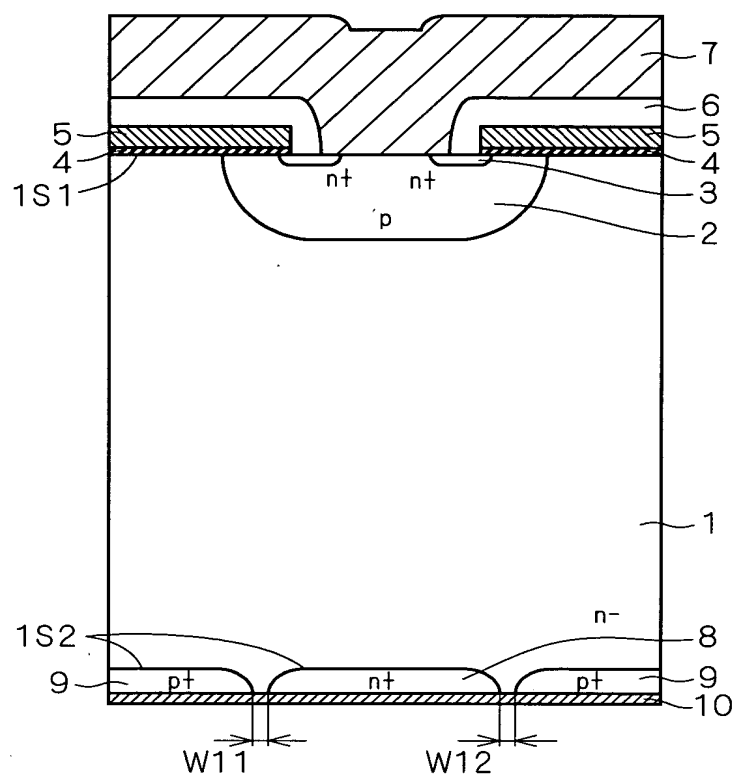




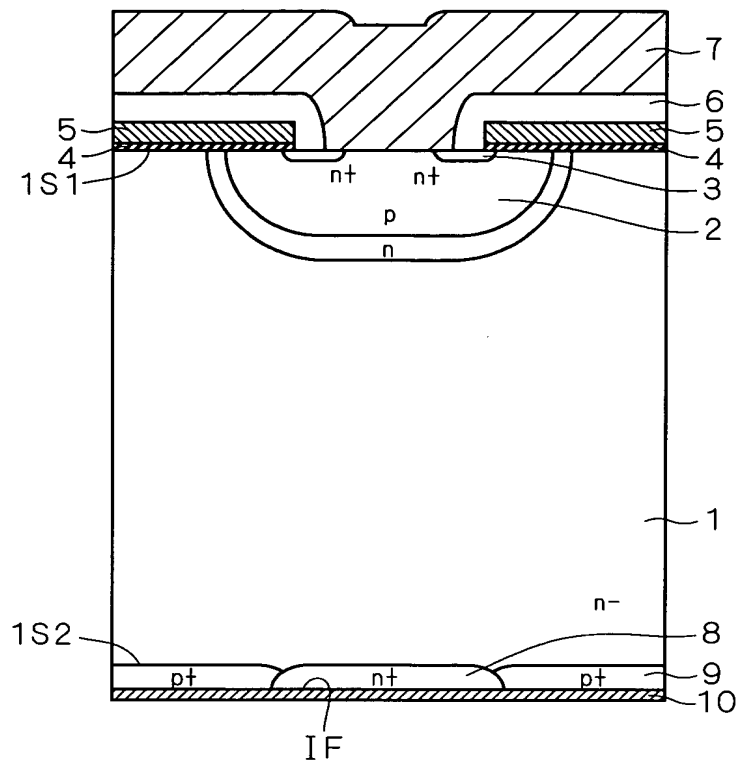
F I G . 1 0



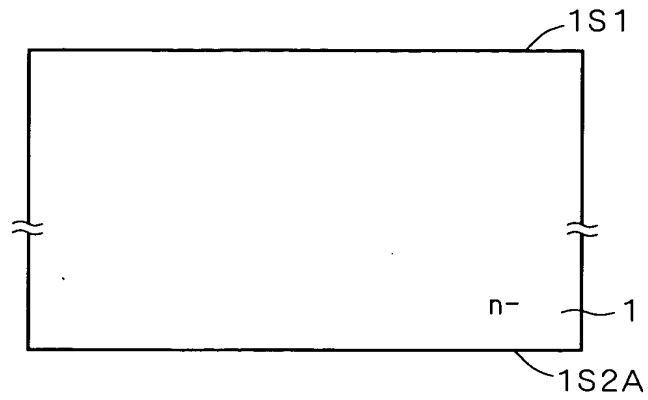
F I G . 1 1



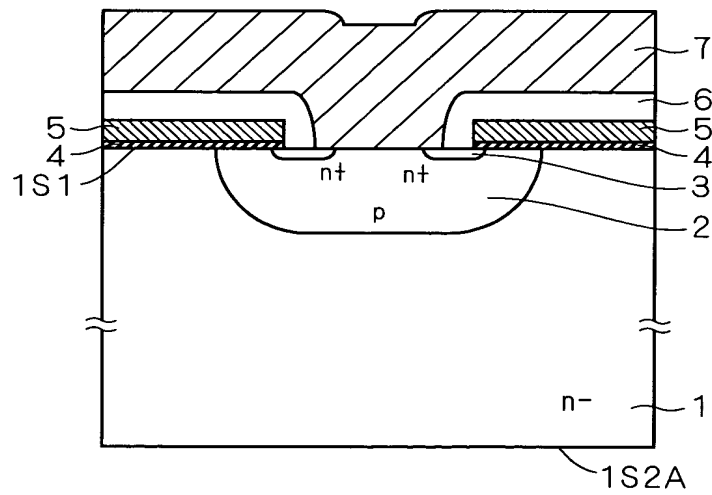
F I G . 1 4



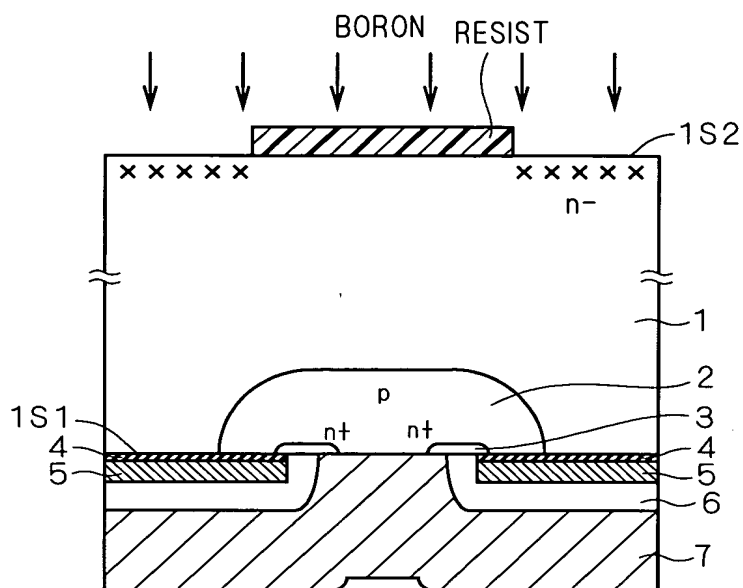
F I G . 1 5



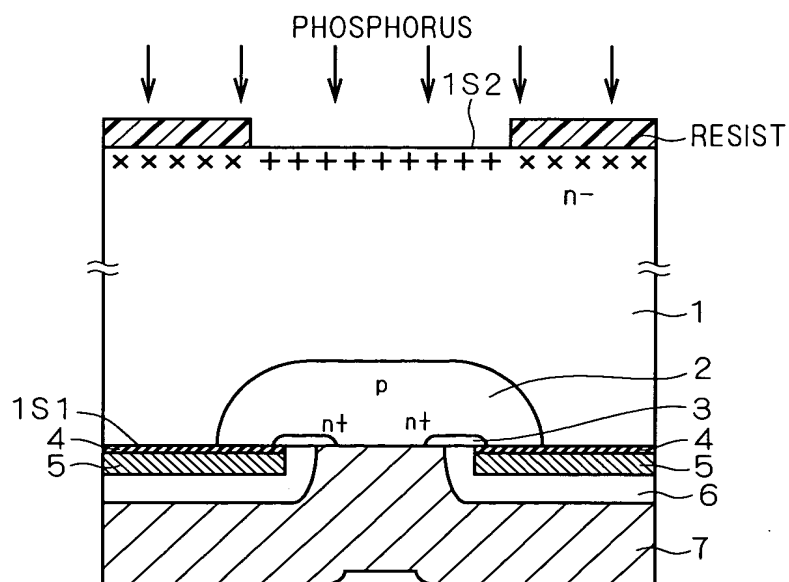
F I G . 1 6



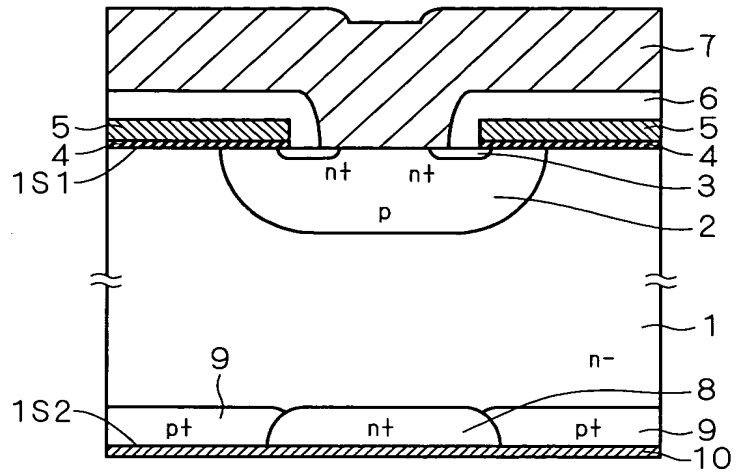
F I G . 1 7



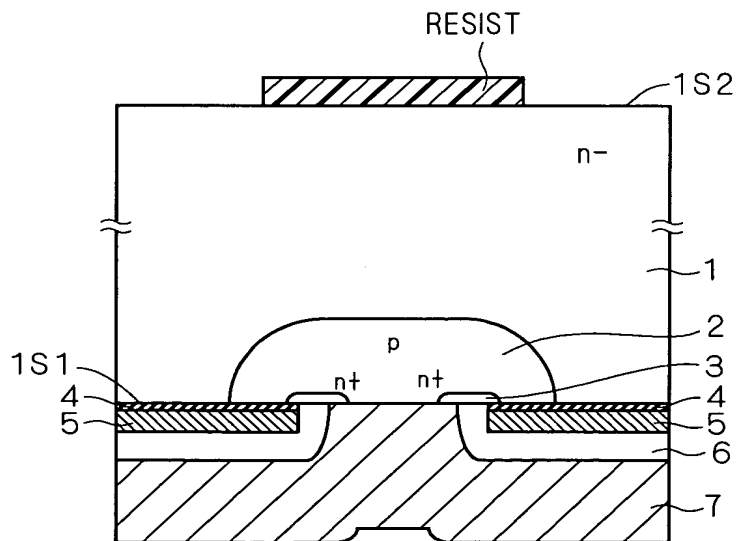
F I G . 1 8



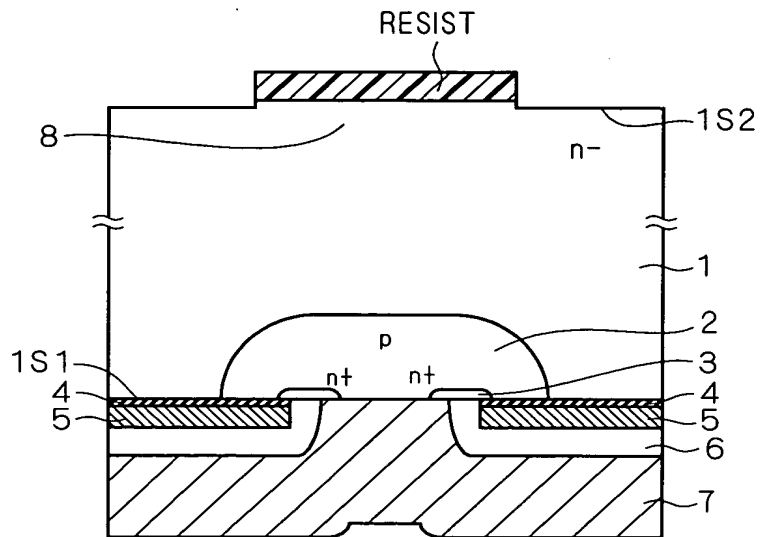
F I G . 1 9



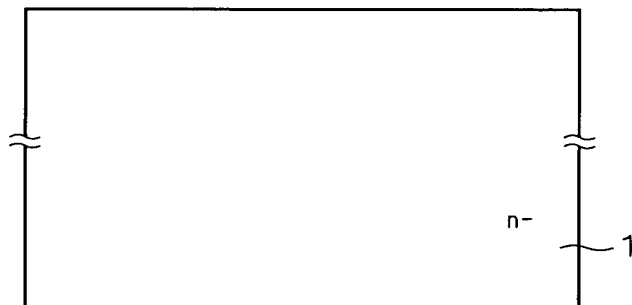
F I G . 2 0



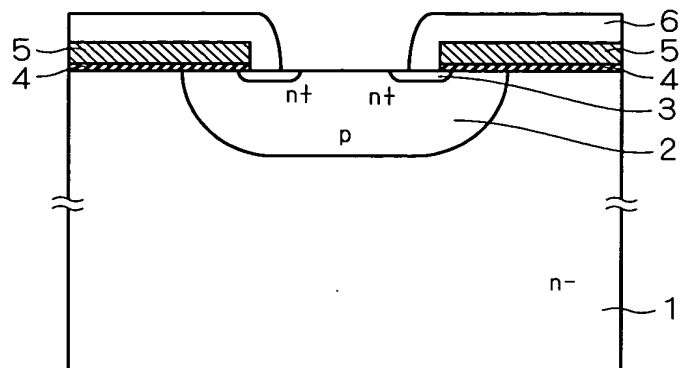
F I G . 2 1



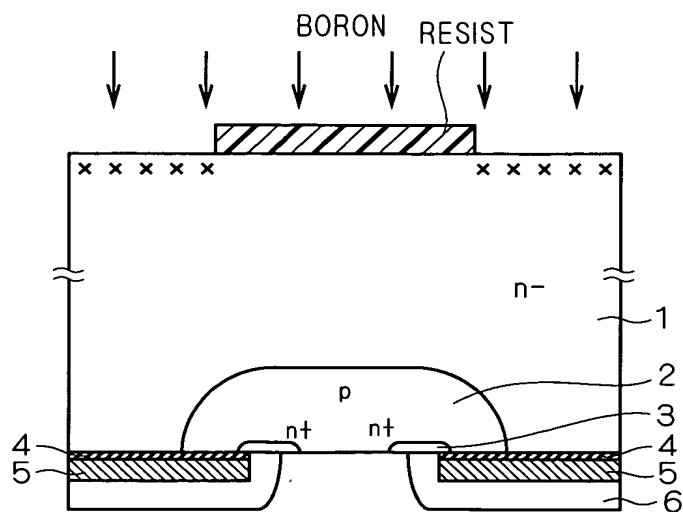
F I G . 2 2



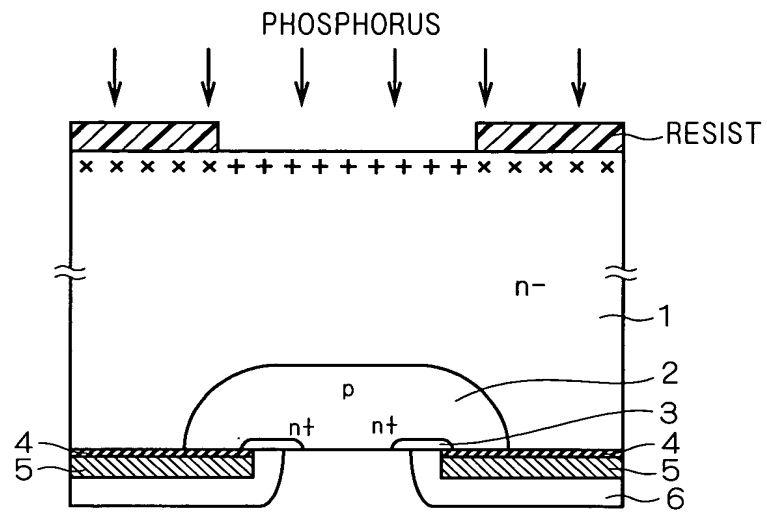
F | G . 2 3



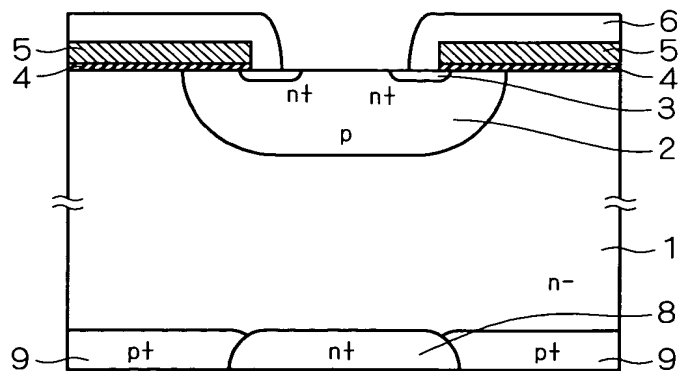
F I G . 2 4



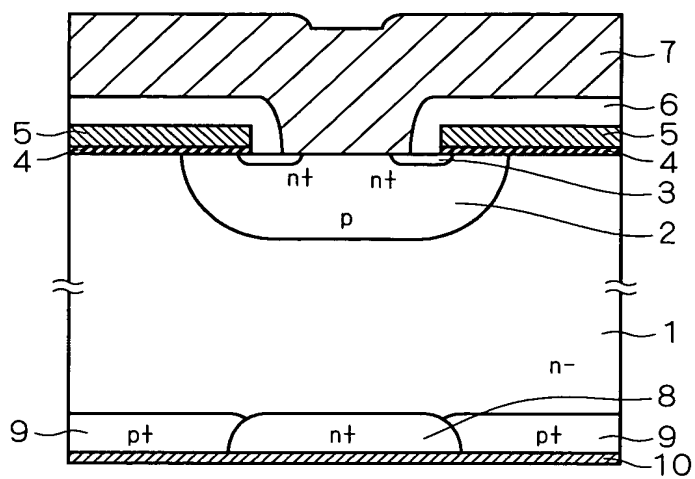
F I G . 2 5



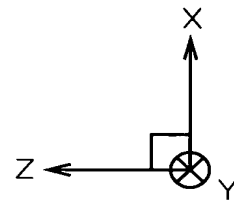
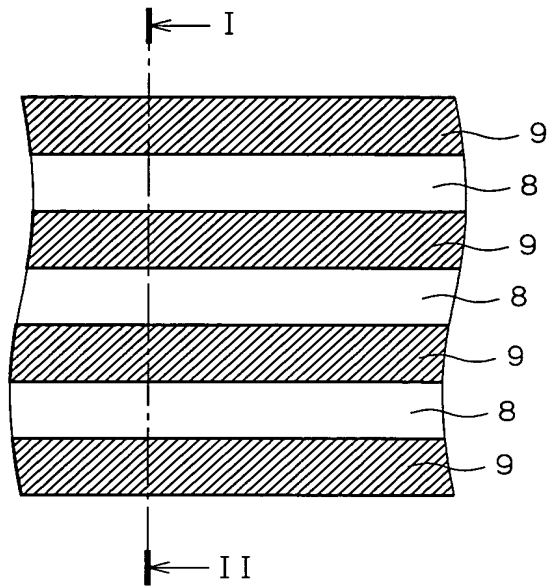
F I G . 2 6



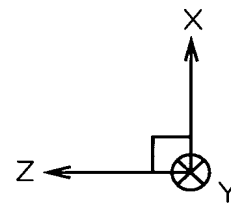
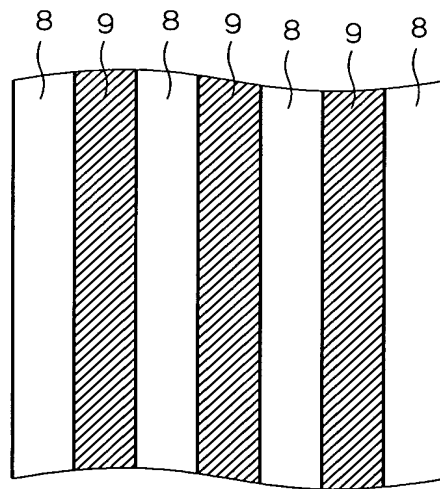
F I G . 2 7



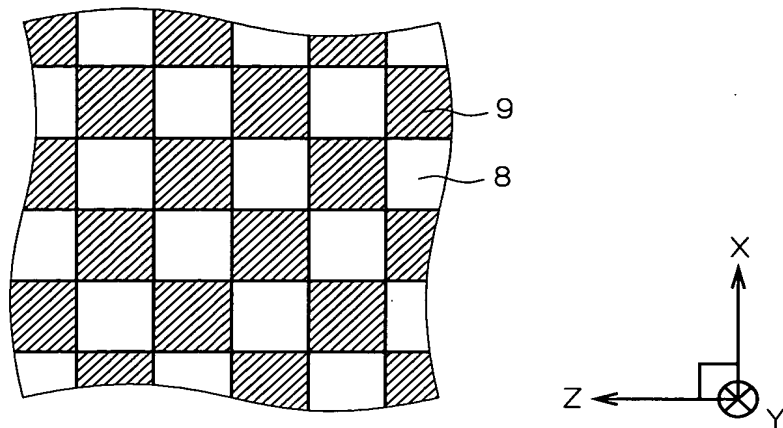
F I G . 2 8



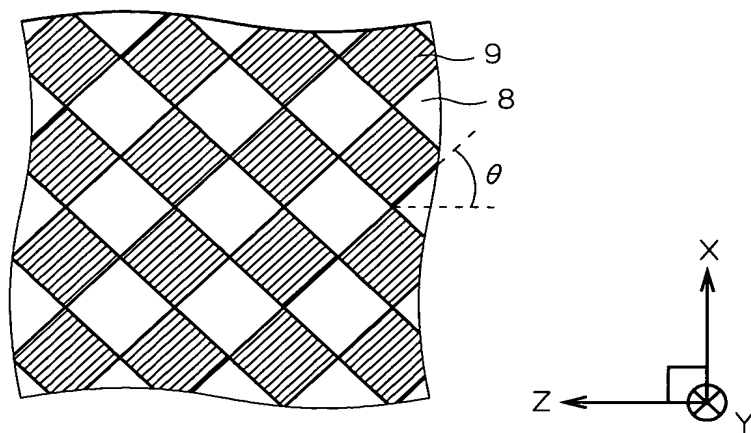
F I G . 2 9



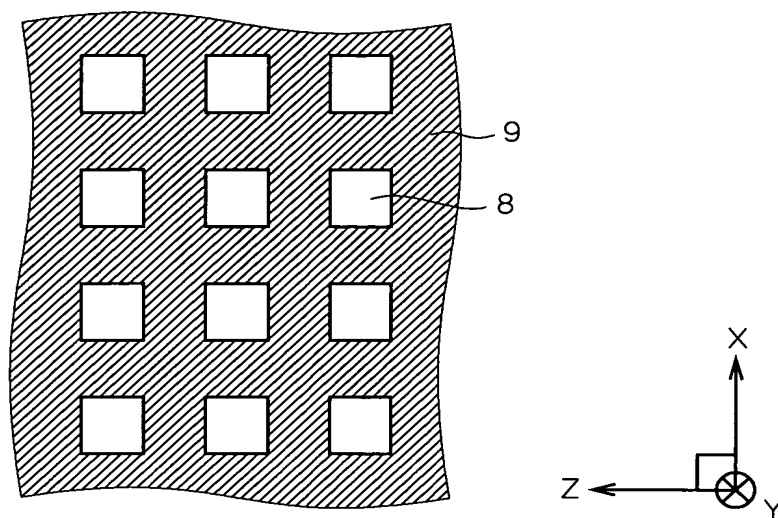
F I G . 3 0



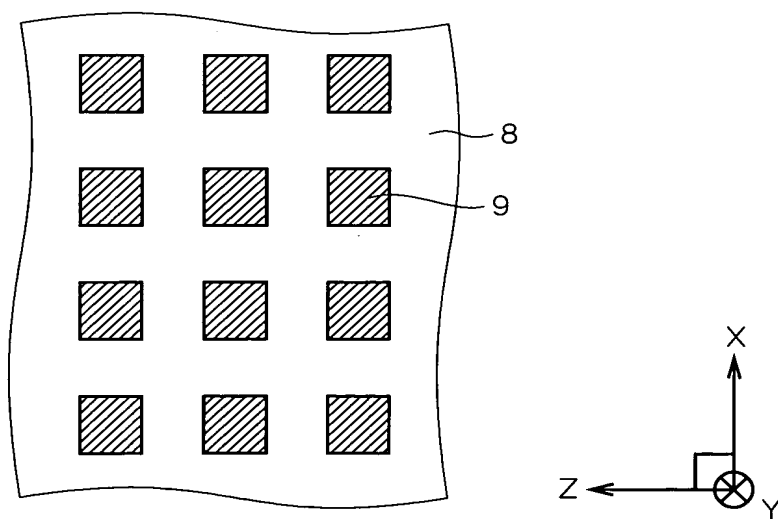
F I G . 3 1



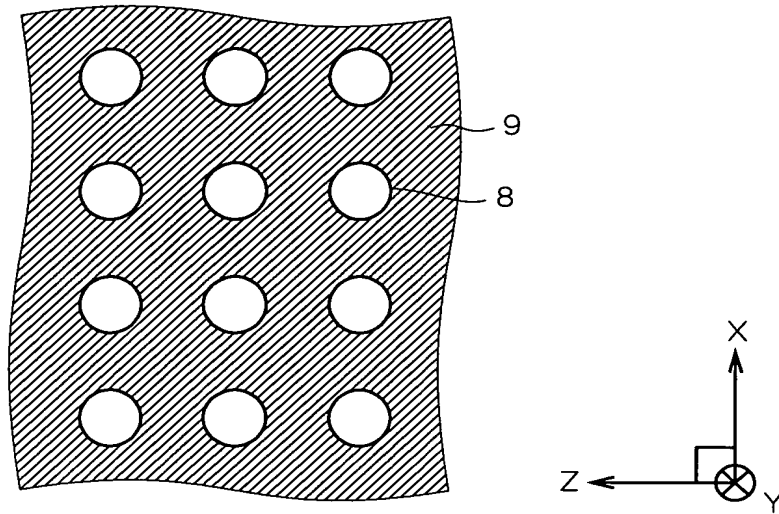
F I G . 3 2



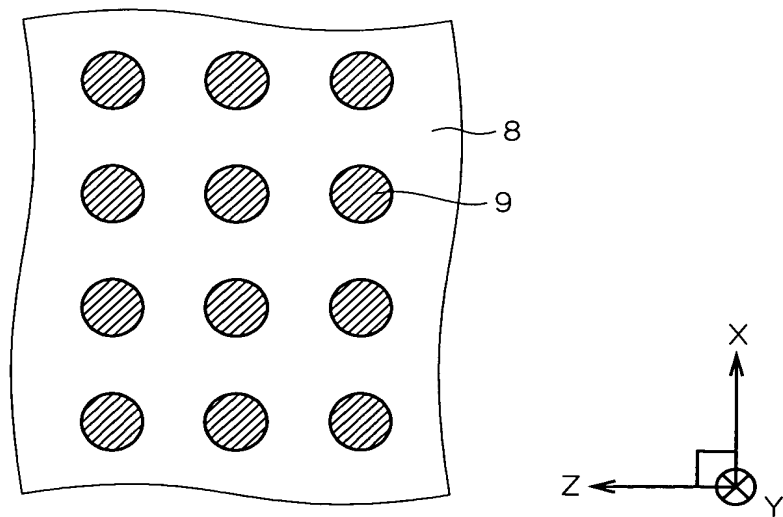
F I G . 3 3



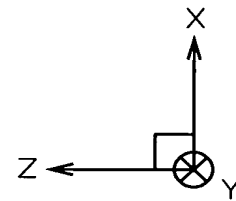
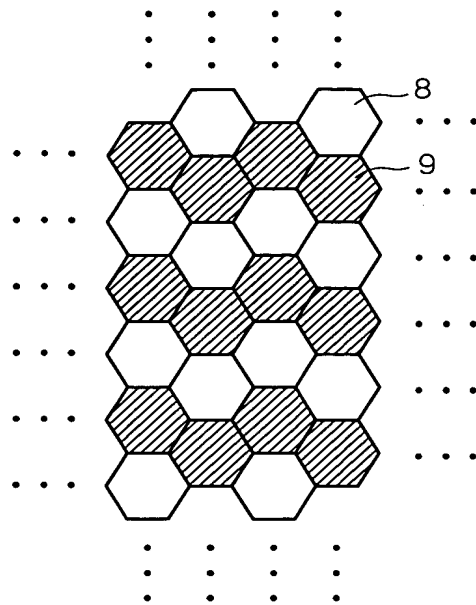
F I G . 3 4



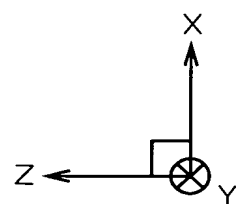
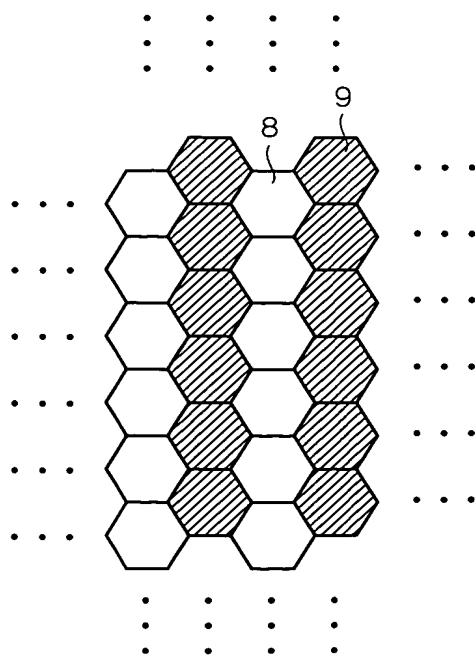
F I G . 3 5



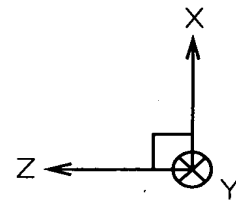
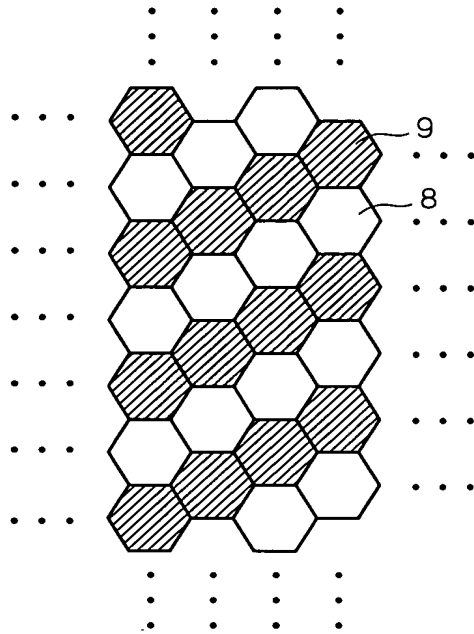
F I G . 3 6



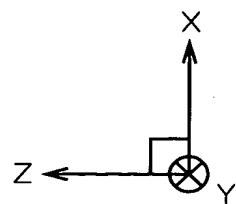
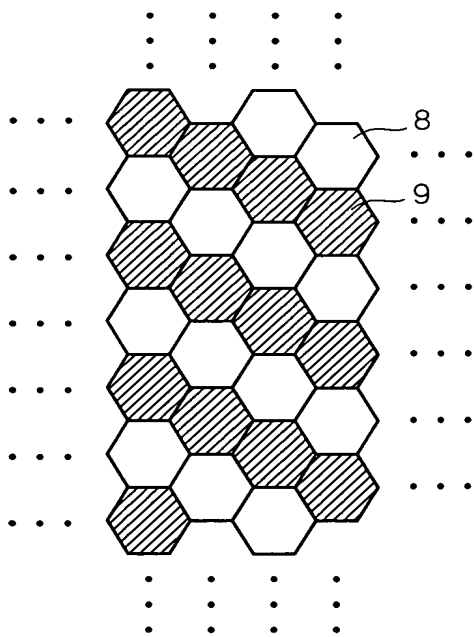
F I G . 3 7



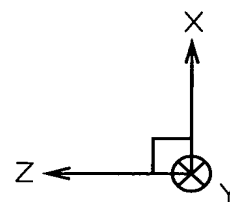
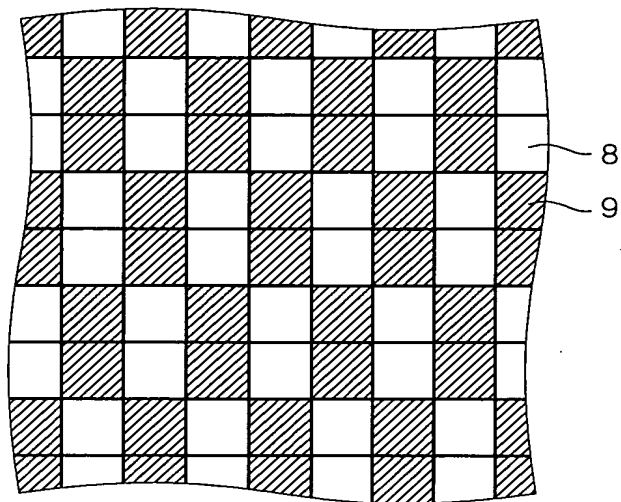
F I G . 3 8



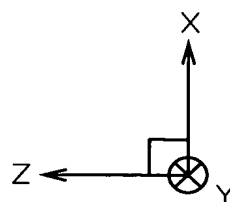
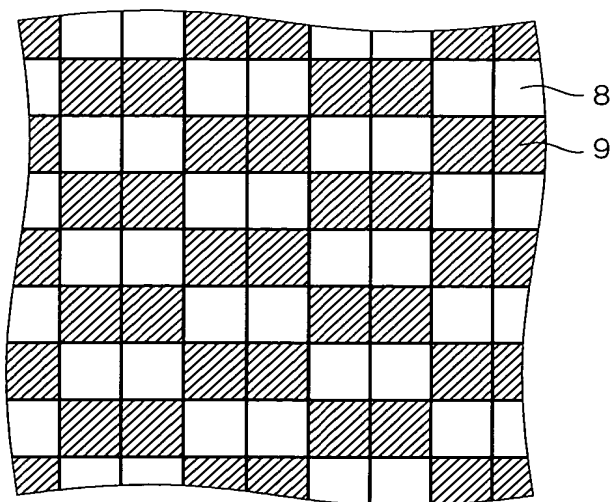
F I G . 3 9



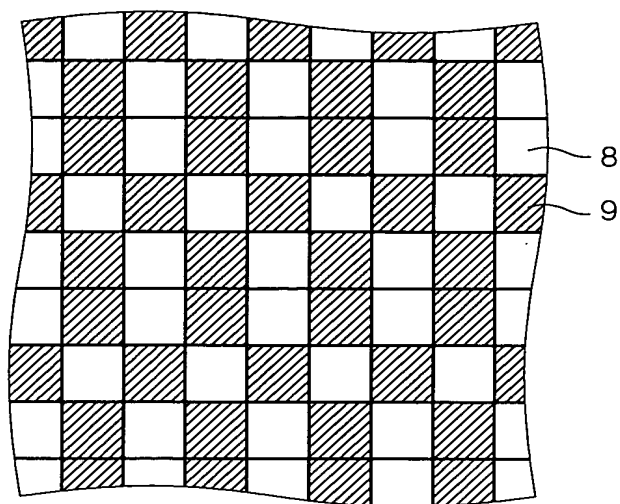
F I G . 4 0



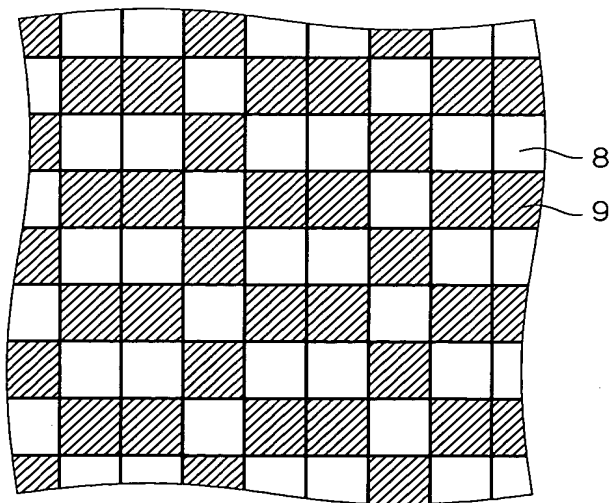
F I G . 4 1



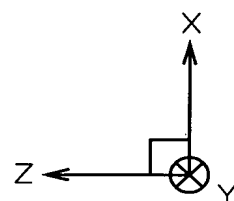
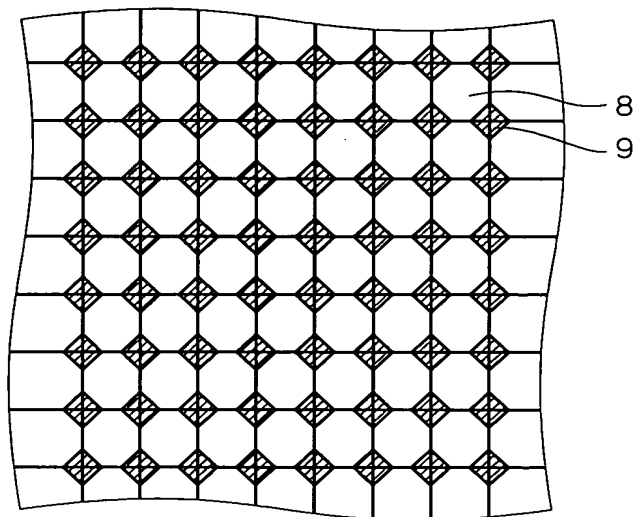
F I G . 4 2



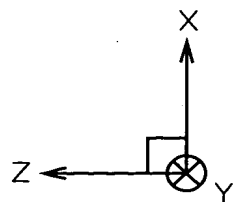
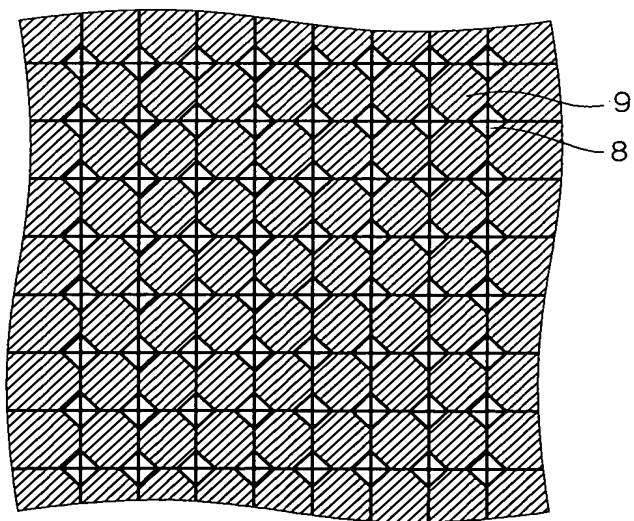
F I G . 4 3



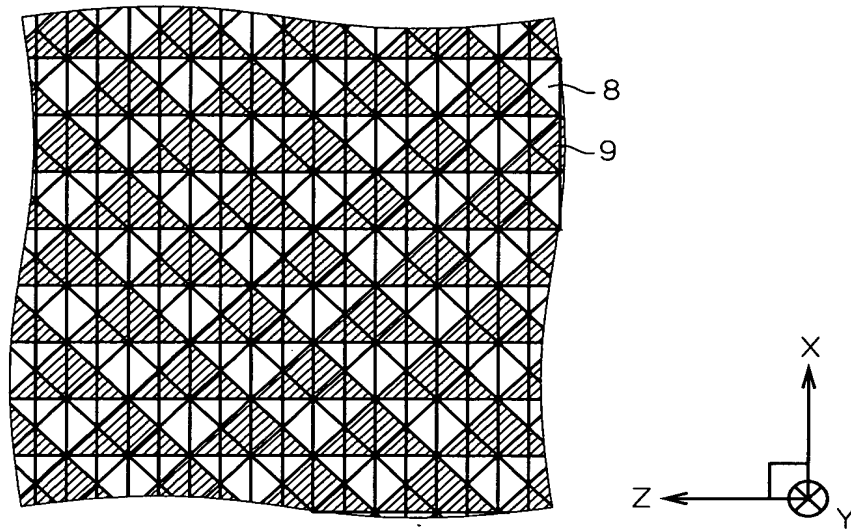
F I G . 4 4



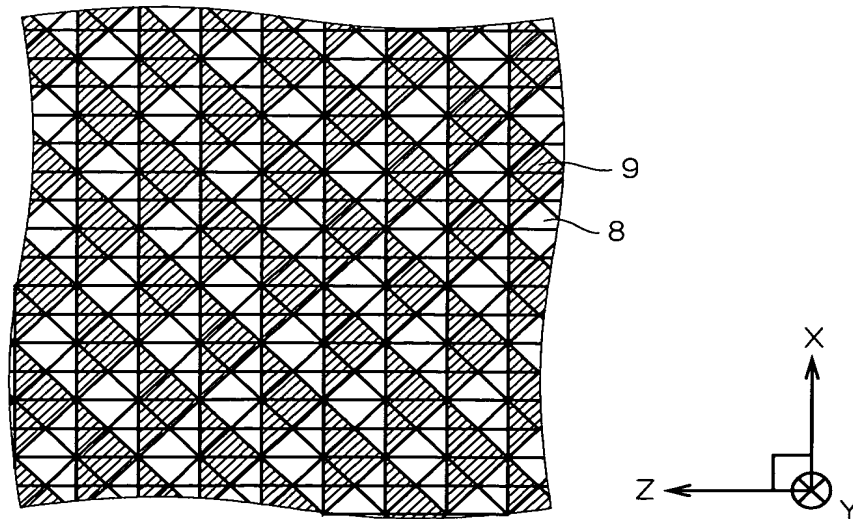
F I G . 4 5



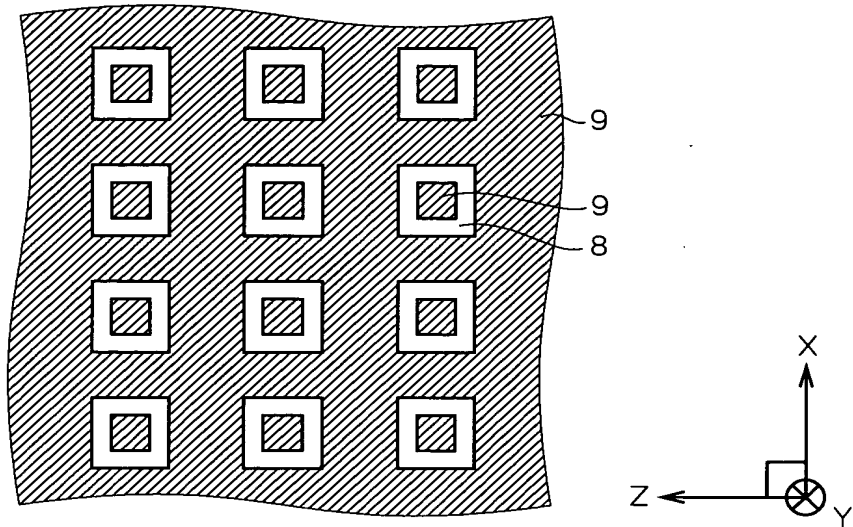
F I G . 4 6



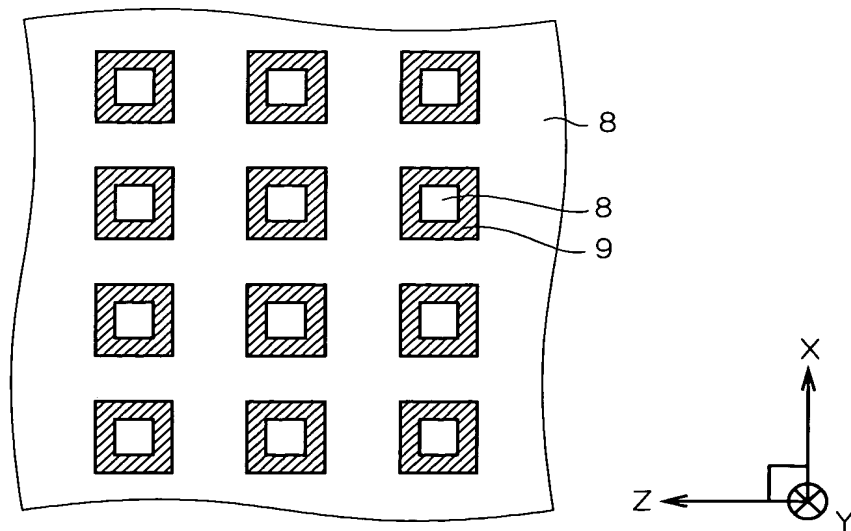
F I G . 4 7



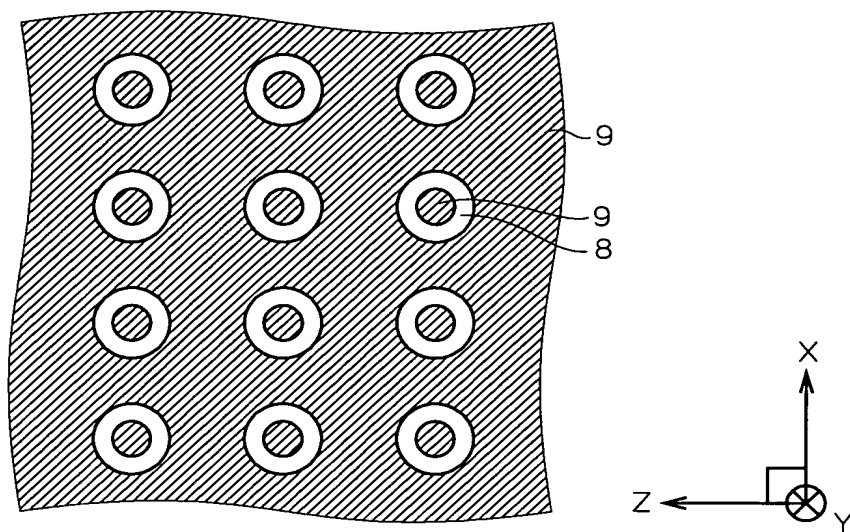
F I G . 4 8



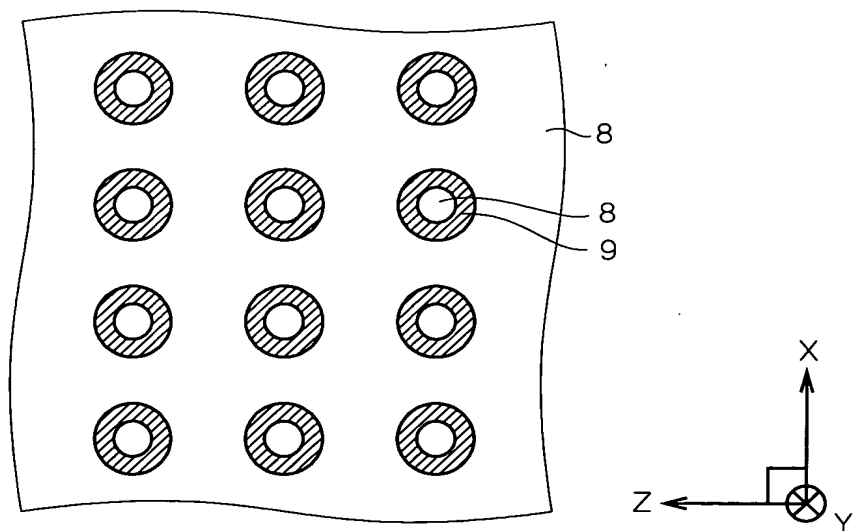
F I G . 4 9



F I G . 5 0



F I G . 5 1



F I G . 5 2

